

### FEATURES

- ✧ High current capability, low forward voltage
- ✧ Excellent high temperature stability
- ✧ Low power loss, and high efficiency
- ✧ High forward surge capability
- ✧ RoHS compliant, and Halogen free

### MACHANICAL DATA

- ✧ Case: TO-277B small outline plastic package
- ✧ Terminal: Matte tin plated, solderable per MIL-STD-750, Method 2026
- ✧ Molding Compound Flammability Rating:UL94-0
- ✧ High temperature soldering guaranteed: 260°C /10second
- ✧ Packed with FRP substrate and epoxy underfilled

### ORDERING INFORMATION

- ✧ Device: SD1060SL
- ✧ Package: TO-277B
- ✧ Marking: 1060
- ✧ Material: Halogen free
- ✧ Packing: Tape & 13" Reel
- ✧ Quantity per reel: 5,000pcs

### APPLICATIONS

- ✧ Switching mode power supply applications
- ✧ Portable equipment battery applications
- ✧ High frequency rectification
- ✧ DC/DC converter
- ✧ Designed as bypass diodes for solar panels

### PIN CONFIGURATION



### PACKAGE OUTLINE



### ABSOLUTE MAXIMUM RATING (Tamb=25°C, unless otherwise specified)

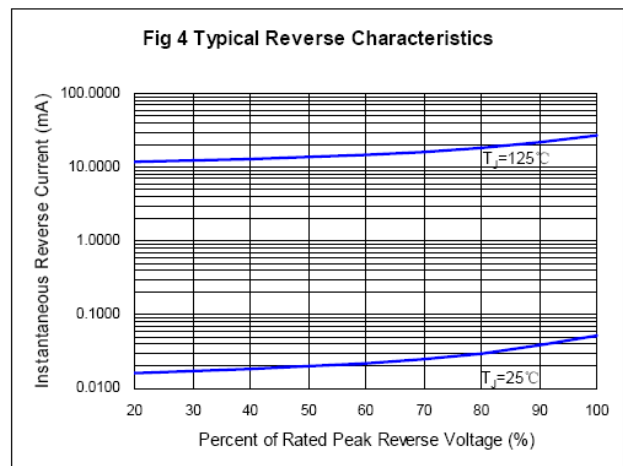
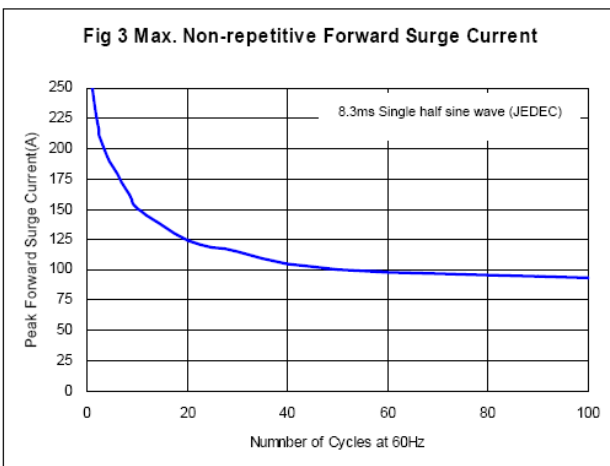
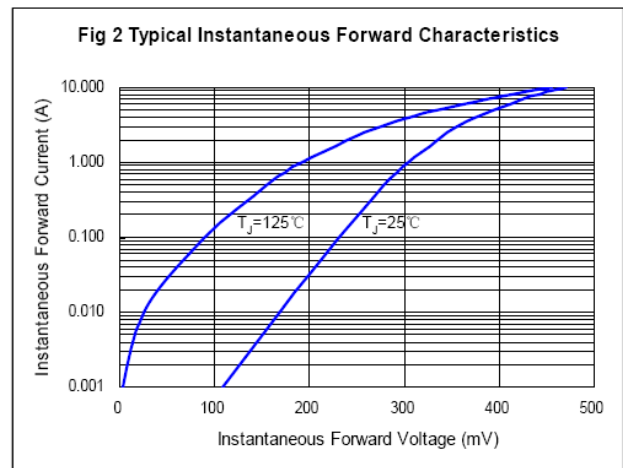
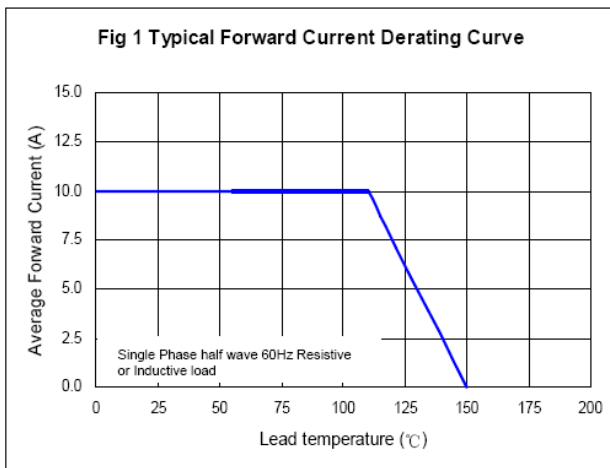
| Symbol            | Parameter   | Value    | Units |
|-------------------|---|----------|-------|
| $V_{RRM}$         | Repetitive Peak Reverse Voltage                         | 60       | V     |
| $I_{F(AV)}$       | Average Forward Current                                 | 10       | A     |
| $I_{FSM}$         | Peak Forward Surge Current, 8.3ms single half sine-wave | 250      | A     |
| $T_J$ & $T_{STG}$ | Junction and Storage Temperature                        | -40~+150 | °C    |

### ELECTRICAL CHARACTERISTICS (Tamb=25°C, unless otherwise specified)

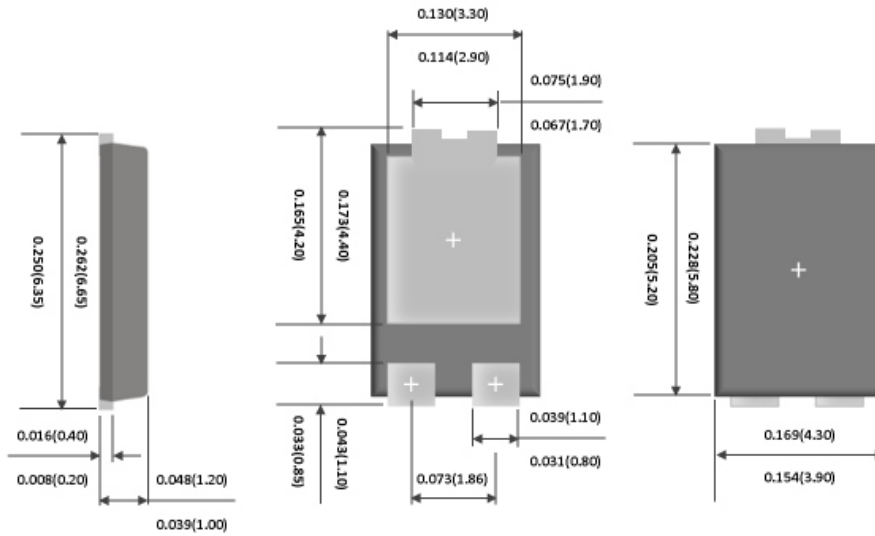
| Symbol              | Parameter                   | Test Condition               | Min | Typ  | Max  | Units |
|---------------------|-----------------------------|------------------------------|-----|------|------|-------|
| V <sub>F</sub>      | Forward Voltage             | I <sub>F</sub> = 3A @ 25°C   |     | 0.36 |      | V     |
|                     |                             | I <sub>F</sub> = 5A @ 25°C   |     | 0.40 | 0.46 | V     |
|                     |                             | I <sub>F</sub> = 10A @ 25°C  |     | 0.47 | 0.53 | V     |
|                     |                             | I <sub>F</sub> = 3A @ 125°C  |     | 0.28 |      | V     |
|                     |                             | I <sub>F</sub> = 5A @ 125°C  |     | 0.34 | 0.40 | V     |
|                     |                             | I <sub>F</sub> = 10A @ 125°C |     | 0.45 | 0.50 | V     |
| I <sub>R</sub>      | Reverse Leakage Current     | V <sub>R</sub> = 60V @ 25°C  |     |      | 0.3  | mA    |
|                     |                             | V <sub>R</sub> = 60V @ 125°C |     |      | 30   | mA    |
| C <sub>J</sub>      | Junction Capacitance        | f=1MHz, V <sub>R</sub> =4V   |     | 550  |      | pF    |
| R <sub>th(JA)</sub> | Thermal Resistance (note 1) |                              |     | 31   |      | °C/W  |

Note 1: Polyimide PCB, 2oz. copper. Cathode pad dimensions 18.8x14.4mm. Anode pad dimensions 5.6x14.4mm

### ELECTRICAL CHARACTERISTICS CURVE

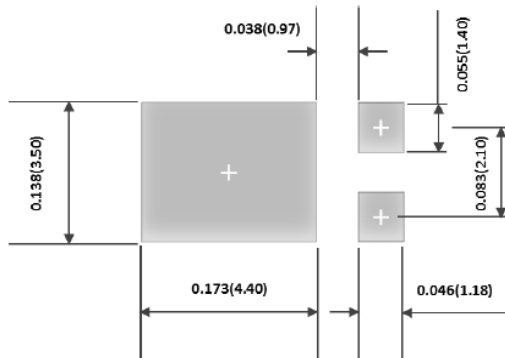


## TO-277B PACKAGE OUTLINE DIMENSIONS



unit: mm

## FOOT PRINT RECOMMENDATION



unit: mm

## MARKING CODE



|             |            |                                 |
|-------------|------------|---------------------------------|
| 1060        | YYYY       | XXX                             |
| Device name | Trace code | Date code                       |
|             |            | XXX                             |
|             |            |                                 |
|             |            | XX=month(01,02,03,04,...,11,12) |
|             |            | X=year(2=2012,3=2013,4=2014...) |